

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



NDS355AN

N-Channel Logic Level Enhancement Mode Field Effect Transistor

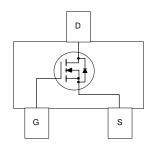
General Description

SuperSOTTM-3 N-Channel logic level enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMCIA cards, and other battery powered circuits where fast switching, and low in-line power loss are needed in a very small outline surface mount package.

Features

- Industry standard outline SOT-23 surface mount package using proprietary SuperSOT[™]-3 design for superior thermal and electrical capabilities.
- High density cell design for extremely low R_{DS(ON)}.
- Exceptional on-resistance and maximum DC current capability.
- Compact industry standard SOT-23 surface mount package.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		NDS355AN	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage - Continuous		±20	V
I _D	Maximum Drain Current - Continuous	(Note 1a)	1.7	А
	- Pulsed		10	
P_{D}	Maximum Power Dissipation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T _J ,T _{STG}	Operating and Storage Temperature Range		-55 to 150	°C
THERMA	L CHARACTERISTICS	<u>.</u>		
R _{eJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
R _{eJC}	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHA	RACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V				1	μΑ
			T _J =125°C			10	μΑ
I _{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 20 V_{DS} = 0 V$				100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHAR	ACTERISTICS (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1	1.6	2	V
			T _J =125°C	0.5	1.2	1.5	
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_{D} = 1.7 \text{ A}$	•		0.105	0.125	Ω
			T _J =125°C		0.16	0.23	
		$V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$	•		0.065	0.085	
I _{D(ON)}	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$		6			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 1.7 \text{ A}$			3.5		S
DYNAMIC	CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			195		pF
C _{oss}	Output Capacitance				135		pF
C _{rss}	Reverse Transfer Capacitance				48		pF
SWITCHI	NG CHARACTERISTICS (Note 2)						
$t_{d(on)}$	Turn - On Delay Time	$V_{DD} = 10 \text{ V}, I_{D} = 1 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$			10	20	ns
t _r	Turn - On Rise Time				13	25	ns
$t_{d(off)}$	Turn - Off Delay Time				13	25	ns
t _f	Turn - Off Fall Time				4	10	ns
$t_{d(on)}$	Turn - On Delay Time	$V_{DD} = 5 \text{ V}, I_D = 1 \text{ A},$ $V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$			10	20	ns
t _r	Turn - On Rise Time				32	60	ns
t _{d(off)}	Turn - Off Delay Time				10	20	ns
t _f	Turn - Off Fall Time				5	10	ns
Q _g	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_{D} = 1.7 \text{ A},$ $V_{GS} = 5 \text{ V}$			3.5	5	nC
Q_{gs}	Gate-Source Charge				8.0		nC
Q_{gd}	Gate-Drain Charge				1.7		nC

Electrical Characteristics (T _A = 25°C unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Тур	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Is	Maximum Continuous Drain-Source Diode Forward Current				0.42	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				10	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.42 \text{ A (Note 2)}$		0.8	1.2	V

Notes:

1. $R_{g,k}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{g,k}$ is guaranteed by design while R_{gCA} is determined by the user's board design.

$$P_D(t) = \frac{T_J - T_A}{R_{\theta J} \hat{A}t} = \frac{T_J - T_A}{R_{\theta J} \hat{C}^R R_{\theta C} \hat{A}^t} = I_D^2(t) \times R_{DS (ON)} \mathcal{C}_{TJ}$$

Typical $R_{\theta^{JA}}$ using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

a. 250°C/W when mounted on a 0.02 in² pad of 2oz copper.

b. 270°C/W when mounted on a 0.001 in 2 pad of 2oz copper.





Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

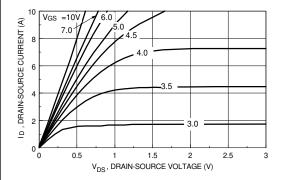


Figure 1. On-Region Characteristics.

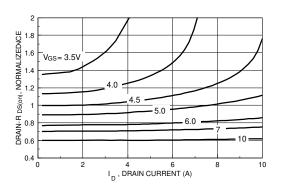


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

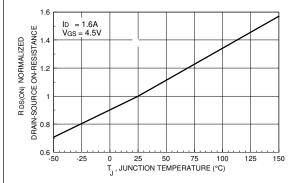


Figure 3. On-Resistance Variation with Temperature.

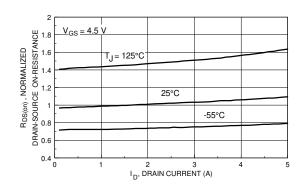


Figure 4. On-Resistance Variation with Drain Current and Temperature.

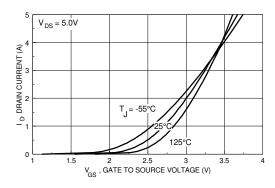


Figure 5. Transfer Characteristics.

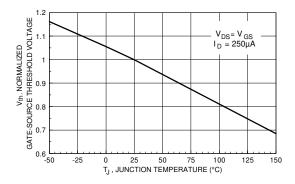


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

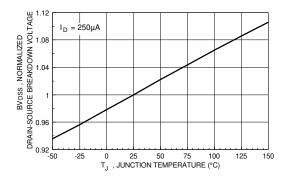


Figure 7. Breakdown Voltage Variation with Temperature.

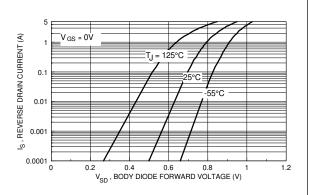


Figure 8. Body Diode Forward Voltage Variation with Source Current and Temperature.

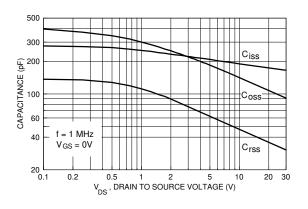


Figure 9. Capacitance Characteristics.

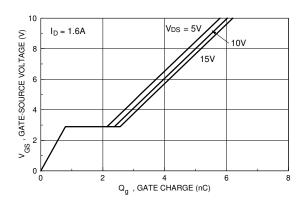


Figure 10. Gate Charge Characteristics.

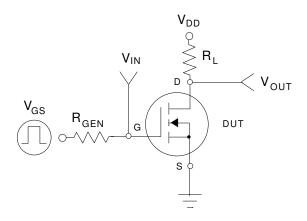


Figure 11. Switching Test Circuit.

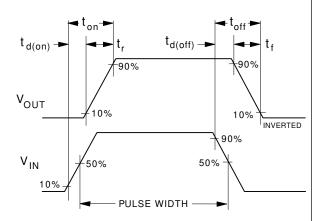
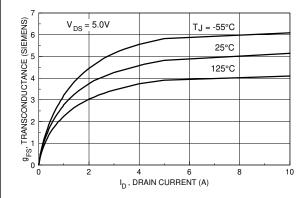


Figure 12. Switching Waveforms.

Typical Electrical Characteristics (continued)



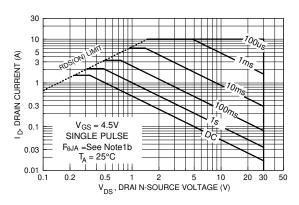
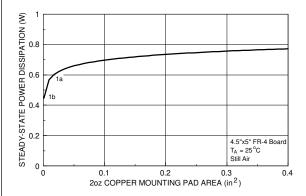
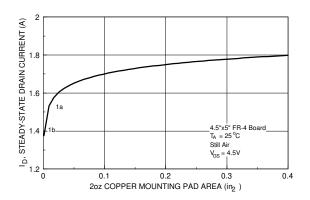


Figure 13. Transconductance Variation with Drain Current and Temperature.

Figure 14. Maximum Safe Operating Area.





Figue 15. SuperSOT[™]-3 Maximum
Steady-State Power Dissipation versus Copper
Mounting Pad Area.

Figure 16. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.

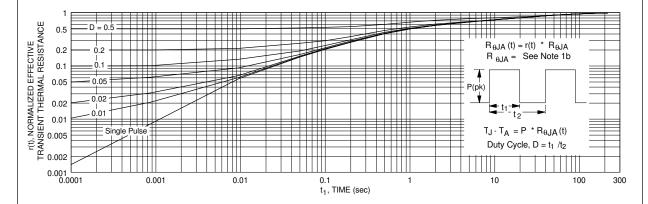


Figure 17. Transient Thermal Response Curve.

Note: Characterization performed using the conditions described in note 1b. Transient thermal response will change depending on the circuit board design.

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

FAST ® SMART START™ VCX^{TM} ACEx™ OPTOLOGIC™ STAR*POWER™ FASTr™ Bottomless™ OPTOPLANAR™ Stealth™ CoolFET™ FRFET™ PACMANTM SuperSOT™-3 CROSSVOLT™ GlobalOptoisolator™ POP™ SuperSOT™-6 DenseTrench™ GTO™ Power247™ $\mathsf{HiSeC^{\mathsf{TM}}}$ SuperSOT™-8 DOME™ PowerTrench® SyncFET™ ISOPLANAR™ EcoSPARK™ QFET™ TinyLogic™ E²CMOSTM LittleFET™ OSTM EnSigna™ MicroFET™ TruTranslation™ QT Optoelectronics™ MicroPak™ UHC™ FACT™ Quiet Series™ UltraFET® FACT Quiet Series™ MICROWIRE™ SILENT SWITCHER®

STAR*POWER is used under license

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS. NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. H4

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor nessure any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, a

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative